

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current	I <sub>PP</sub>	3	A	8/20μs, per Figure 3
ESD Protection – Contact Discharge	V <sub>ESD_Contact</sub>	±10	kV	IEC 61000-4-2 Standard

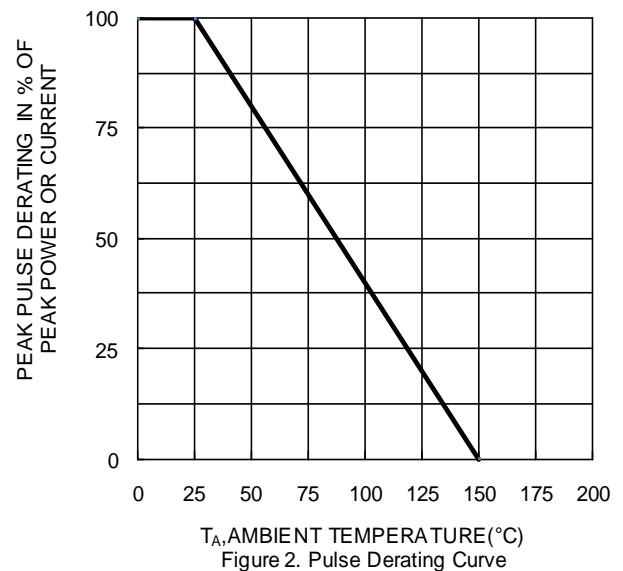
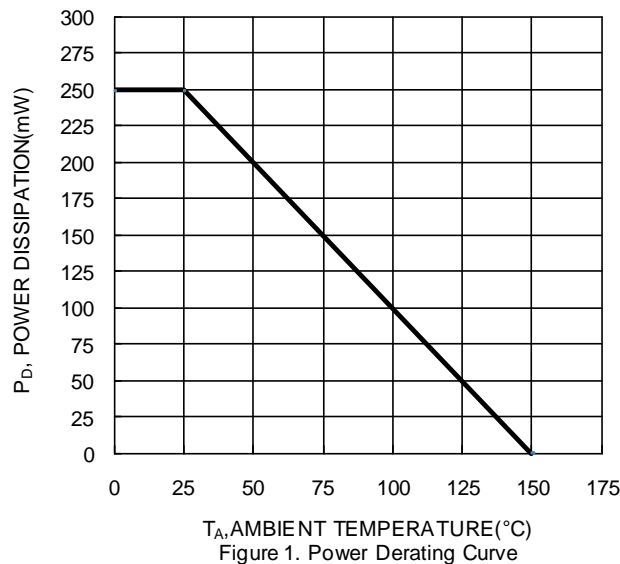
**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P <sub>D</sub>	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Standoff Voltage	V <sub>RWM</sub>	-	-	5	V	-
Channel Leakage Current (Note 6)	I <sub>RM</sub>	-	5	100	nA	V <sub>RWM</sub> = 5V
Clamping Voltage	V <sub>CL</sub>	-	7.2	-	V	I <sub>PP</sub> = 3A, t <sub>p</sub> = 8/20μs
Breakdown Voltage	V <sub>BR</sub>	5.5	7	9.5	V	I <sub>R</sub> = 5mA
Differential Resistance	R <sub>DIF</sub>	-	-	100	Ω	I <sub>R</sub> = 1mA
Dynamic Impedance	R <sub>dyn</sub>	-	0.3	-	Ω	TLP, 20A, t <sub>p</sub> = 100 ns
Channel Input Capacitance	C <sub>T</sub>	-	2.9	-	pF	V <sub>R</sub> = 0V, f = 1MHz
		-	1.9	-		V <sub>R</sub> = 5V, f = 1MHz

Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.  
 6. Short duration pulse test used to minimize self-heating effect.



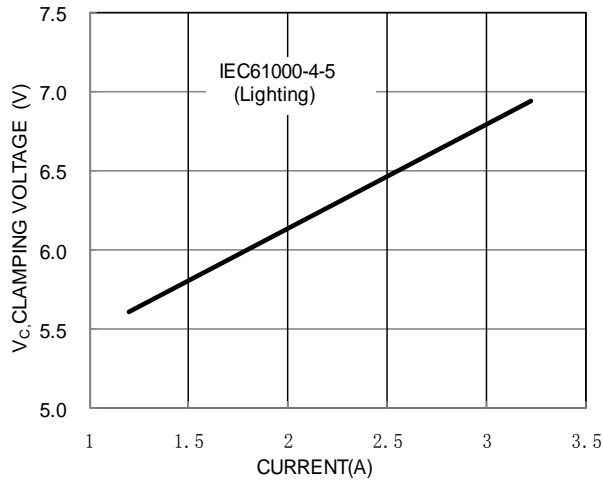


Figure 3. Clamping Voltage Characteristic

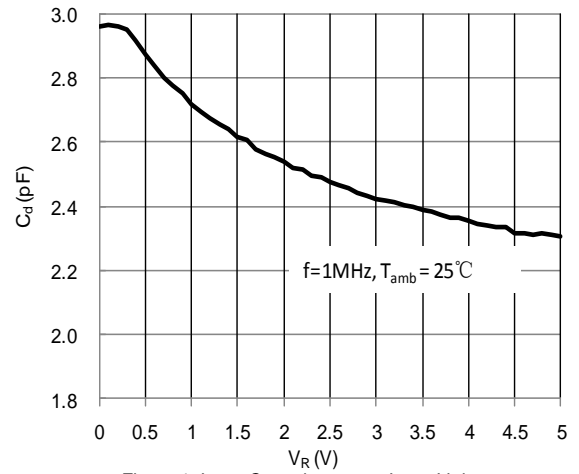


Figure 4. Input Capacitance vs. Input Voltage

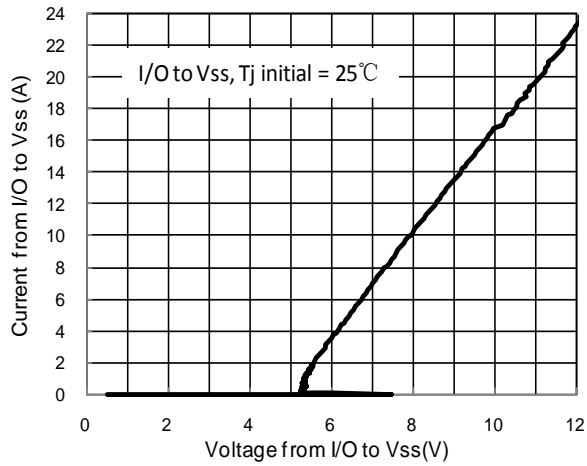


Figure 5. Current vs. Voltage

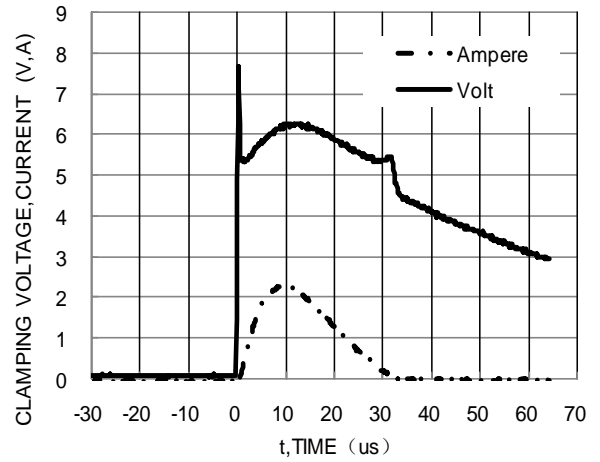


Figure 6. Waveform of Clamping Voltage, Current vs. Time(8/20us, I/O to Vss)

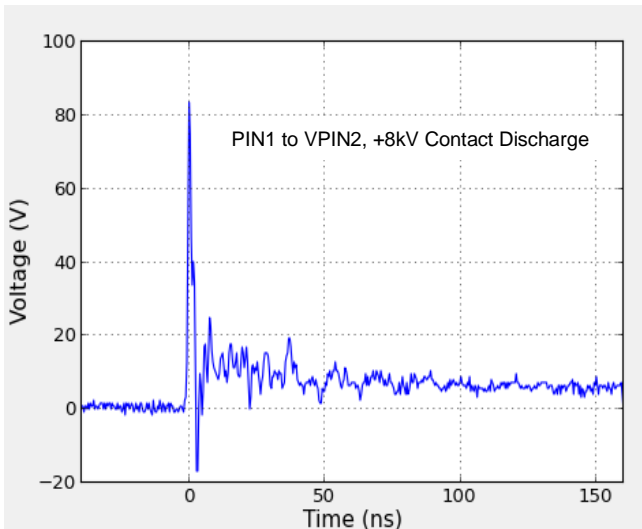


Figure 7 ESD Response to IEC 61000-4-2

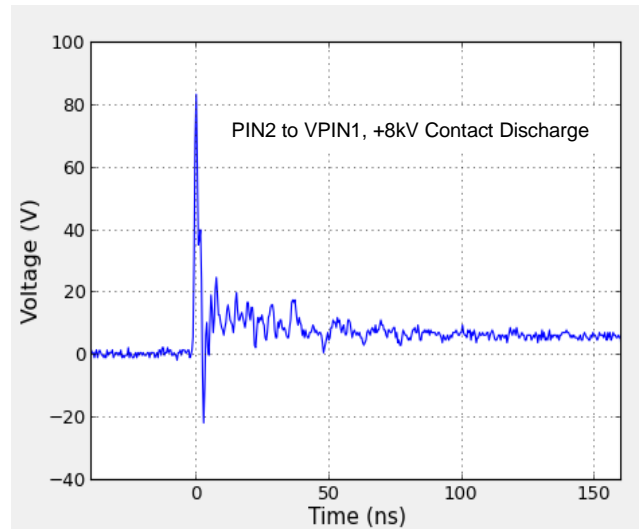
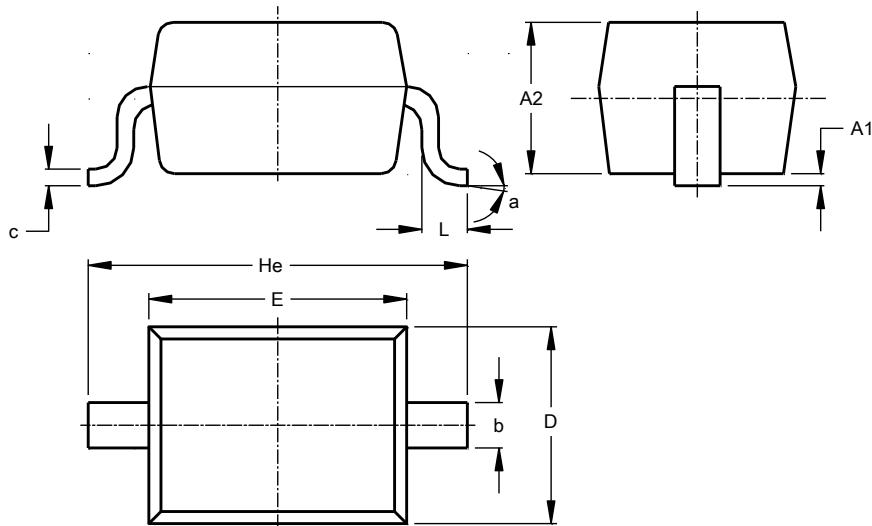


Figure 8 ESD Response to IEC 61000-4-2

## Package Outline Dimensions

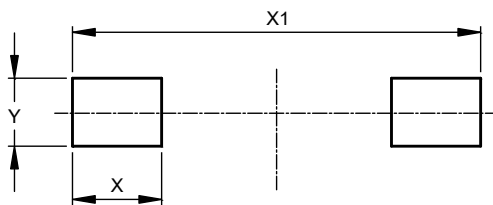
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOD323			
Dim	Min	Max	Typ
A1	-	0.10	0.05
A2	1.00	1.10	1.05
b	0.25	0.35	0.30
c	0.10	0.15	0.11
D	1.20	1.40	1.30
E	1.60	1.80	1.70
He	2.30	2.70	2.50
L	0.20	0.40	0.30
a	8°		
All Dimensions in mm			

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X	0.590
X1	2.700
Y	0.450

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